Amendments to the Specification:

Please amend the paragraph (section) beginning on page 1, at line 5 as shown below:

<u>This application is a continuation of U.S. application Serial No. 09/858,691, filed May 16, 2001.</u>

This application claims the benefit of U.S. provisional application Serial No. 60/204,275, filed May 16, 2000, entitled "Trajectory Generation and Link Optimization." This application is a continuation-in-part of U.S. patent application Serial No. 09/572,925, also filed May 16, 2000, entitled "Method and System for Precisely Positioning a Waist of a Material-Processing Laser Beam to Process Microstructures Within a Laser-Processing Site[[.]]"<u>, now issued as U.S. Patent No. 6,483,071.</u>

Please amend the paragraph (section) beginning on page 7, at line 4 as shown below:

A laser processing system, generally indicated at 110, is shown in Figure 1. A wafer 4 is positioned within the laser processing system 110 and database information from a user interface 11 is provided to identify links (33 in Figure 3) on the wafer 4 which are to be ablated to repair defective memory cells <u>31</u>.

Please amend the paragraph (section) beginning on page 7, at line 8 as shown below:

The database information is used by a trajectory planner 12 and a DSP-based controller 15,16 in conjunction with motion stage 6, 7, calibration to define motion segments for the trajectory generator which are executed and coordinated with a laser, focusing optics, and x-y stage 6, 7 operation to ablate links, as shown in the above-noted utility application. This operation includes control of x-y motion with preferred high-speed precision stages 6, 7 and simultaneous positioning of optical elements to position the beam waist of the processing laser <u>(not shown)</u> to coincide with a coordinate of the link 33 when the laser is pulsed.

Please amend the paragraph (section) beginning on page 8, at line 3 as shown below:

The "trajectory planner" 12 is utilized to plan the path of the wafer 4 and beam waist position [[5]] with a motion system 6, 7, 17 and associated DSP based controller 16. The trajectory planner integrates information from the user interface and alignment system 11 that is used to define the position of the laser relative to the targets (the latter typically mounted on a precision stage, for instance, a wafer stage) in a coordinate system. From the database the information is derived, resulting in a "link map", die selection, and other pertinent data regarding the memory repair operation.